

UWS

Chip Type, High CV
High Temperature (260°C) Reflow



- Corresponding with 260°C peak reflow soldering
Recomended reflow condition : 260°C peak 5 sec. 230°C over 60 sec. 2 times
($\phi 8 \times 6.2$, $\phi 10 \times 10$: 1 time)
- Chip type higher capacitance in large case size.
- Applicable to automatic mounting machine fed with carrier tape.
- Compliant to the RoHS directive (2011/65/EU).

Products which are scheduled to be discontinued.
Not recommended for new designs

UWS

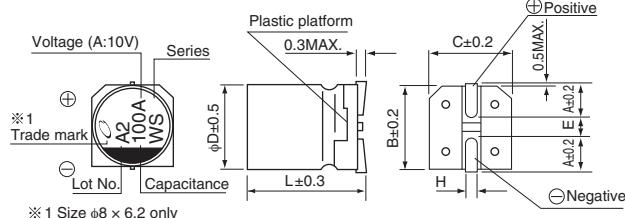
High
Temperature
Reflow

UUR**■ Specifications**

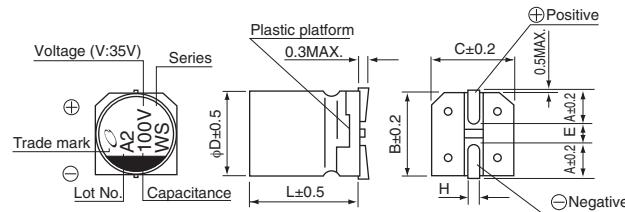
Item	Performance Characteristics								
Category Temperature Range	-40 to +85°C								
Rated Voltage Range	6.3 to 50V								
Rated Capacitance Range	22 to 1500μF								
Capacitance Tolerance	±20% at 120Hz, 20°C								
Leakage Current	After 1 minute's application of rated voltage, leakage current is not more than 0.03CV (μA). Measurement frequency : 120Hz at 20°C								
Tangent of loss angle (tan δ)	Rated voltage (V)	6.3	10	16	25	35	50		
	tan δ (MAX.)	0.28	0.24	0.20	0.16	0.14	0.12		
Stability at Low Temperature	Rated voltage (V)	6.3	10	16	25	35	50		
	Impedance ratio Z-25°C / Z+20°C	5	4	3	2	2	2		
	ZT / Z20 (MAX.) Z-40°C / Z+20°C	10	8	6	4	3	3		
Endurance	The specifications listed at right shall be met when the capacitors are restored to 20°C after the rated voltage is applied for 2000 hours at 85°C.				Capacitance change	Within ±20% of the initial capacitance value			
					tan δ	200% or less than the initial specified value			
					Leakage current	Less than or equal to the initial specified value			
Shelf Life	After storing the capacitors under no load at 85°C for 1000 hours and then performing voltage treatment based on JIS C 5101-4 clause 4.1 at 20°C, they shall meet the specified values for the endurance characteristics listed above.								
Resistance to soldering heat	The capacitors are kept on a hot plate for 30 seconds, which is maintained at 250°C. The capacitors shall meet the characteristic requirements listed at right when they are removed from the plate and restored to 20°C.								
Marking	Black print on the case top.								

■ Chip Type

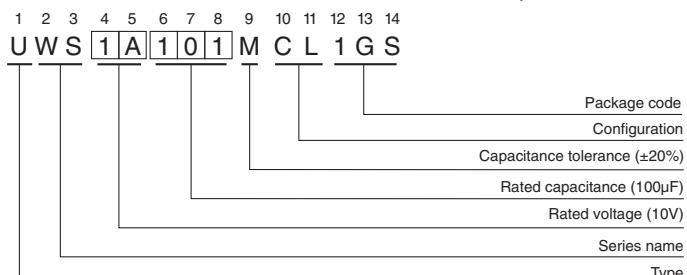
(φ6.3, φ8 × 6.2)



(φ8 × 10, φ10 × 10)



Type numbering system (Example : 10V 100μF)



φDxL	6.3 × 5.8	6.3 × 7.7	8 × 6.2	8 × 10	10 × 10
A	2.4	2.4	3.3	2.9	3.2
B	6.6	6.6	8.3	8.3	10.3
C	6.6	6.6	8.3	8.3	10.3
E	2.2	2.2	2.3	3.1	4.5
L	5.8	7.7	6.2	10	10
H	0.5 to 0.8	0.5 to 0.8	0.5 to 0.8	0.8 to 1.1	0.8 to 1.1

Voltage

V	6.3	10	16	25	35	50
Code	j	A	C	E	V	H

● Dimension table in next page.

UWS

■Dimensions

Cap.(μ F)	Code	V	6.3	10	16	25	35	50
		0J	1A	1C	1E	1V	1H	
22	220							6.3 × 5.8 45
33	330					6.3 × 5.8 55	8 × 6.2 95	
47	470				6.3 × 5.8 65	8 × 6.2 105	8 × 10 140	
100	101		6.3 × 5.8 70	8 × 6.2 125	8 × 6.2 145	8 × 10 175	10 × 10 195	
150	151		6.3 × 5.8 85	6.3 × 7.7 151	8 × 10 192	8 × 10 214	10 × 10 238	
220	221	8 × 6.2 160	8 × 6.2 175	8 × 10 215	10 × 10 250	10 × 10 265	10 × 10 289	
330	331	8 × 6.2 190	8 × 10 240	8 × 10 270	10 × 10 305	10 × 10 324		
470	471	8 × 10 265	8 × 10 290	10 × 10 330	10 × 10 393			
680	681	8 × 10 318	10 × 10 374	10 × 10 396				
1000	102	10 × 10 400	10 × 10 454					Case size Φ D × L (mm) Rated ripple
1500	152	10 × 10 489						

Rated ripple current (mA rms) at 85°C 120Hz

● Frequency coefficient of rated ripple current

Cap.(μ F)	Frequency	50 Hz	120 Hz	300 Hz	1 kHz	10 kHz or more
Less than 47		0.80	1.00	1.15	1.40	1.67
100 to 1500		0.85	1.00	1.08	1.20	1.30

- Taping specifications are given in page 23.
- Recommended land size, soldering by reflow are given in page 18, 19.
- Please refer to page 3 for the minimum order quantity.